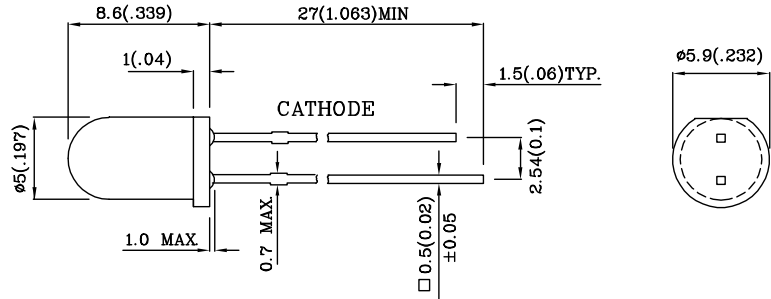


Features

- T-1 3/4 PACKAGE .
- WITH BUILT-IN BLINKING IC.
- OPERATION VOLTAGE FROM 3.5V TO 14V.
- BLINKING FREQUENCY FROM 3.0Hz TO 1.5Hz.
- RoHS COMPLIANT.



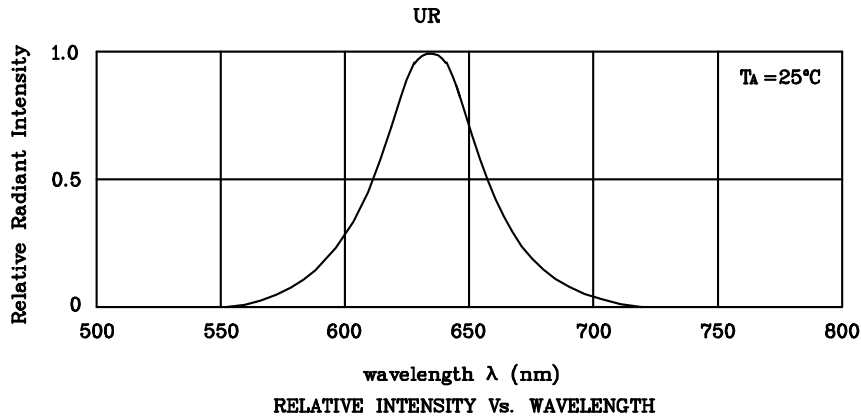
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.

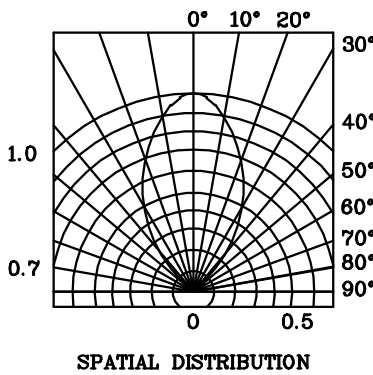
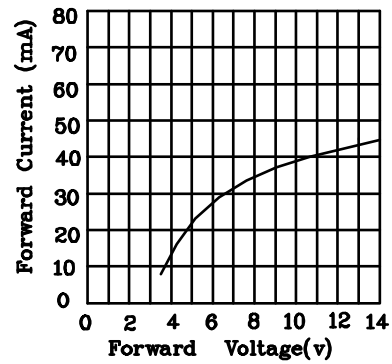
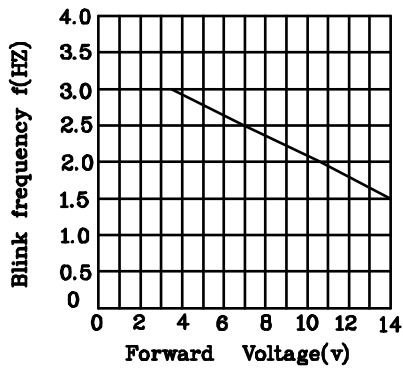
Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)		UR (GaAsP/GaP)	Unit
Reverse Voltage	V_R	0.5	V
Forward Voltage	V_F	14	V
Power Dissipation	P_T	310	mW
Operating Temperature	T_A	-40 ~ +70	°C
Storage Temperature	T_{stg}	-40 ~ +85	
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds		
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds		

Operating Characteristics ($T_A=25^\circ\text{C}$)		UR (GaAsP/GaP)	Unit
Forward Current (Min.) ($V_F=3.5\text{V}$)	I_F	8	mA
Forward Current (Typ.) ($V_R=5\text{V}$)	I_F	22	mA
Supply Current $V_F=3.5\text{V}$	I_{SON}	8	mA
Supply Current $V_F=14\text{V}$	I_{SON}	44	mA
Blink Frequency $V_F=3.5\text{V}$	f	3	Hz
Blink Frequency $V_F=14\text{V}$	f	1.5	Hz
Wavelength of Peak Emission	λ_P	627	nm
Wavelength of Dominant Emission	λ_D	625	nm
Spectral Line Half-Width	$\Delta\lambda$	45	nm

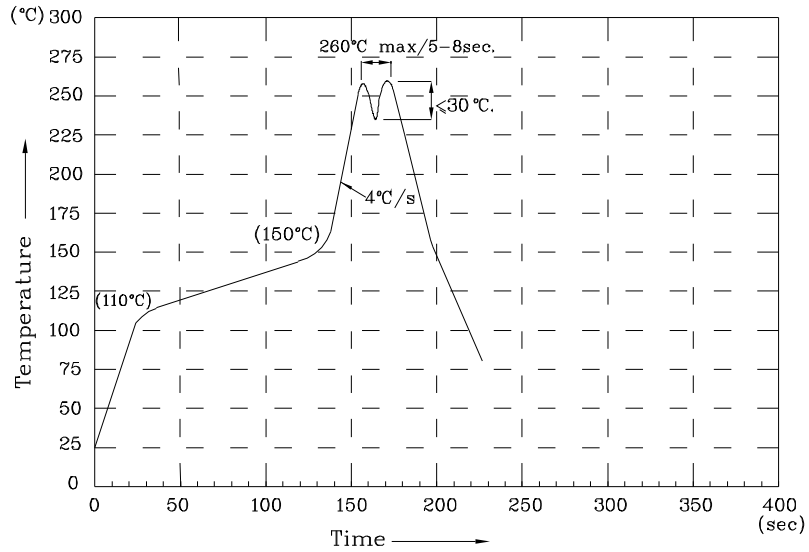
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ($V=9\text{V}$) mcd		Wavelength nm λ_P	Viewing Angle 2θ 1/2
				min.	typ.		
XBUR53D	Red	GaAsP/GaP	Red Diffused	18	39	627	60°
Published Date : MAY 30,2005 Drawing No : XDSA2649 V3 Checked : B.L.LIU P.1/3							



❖ UR



Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.